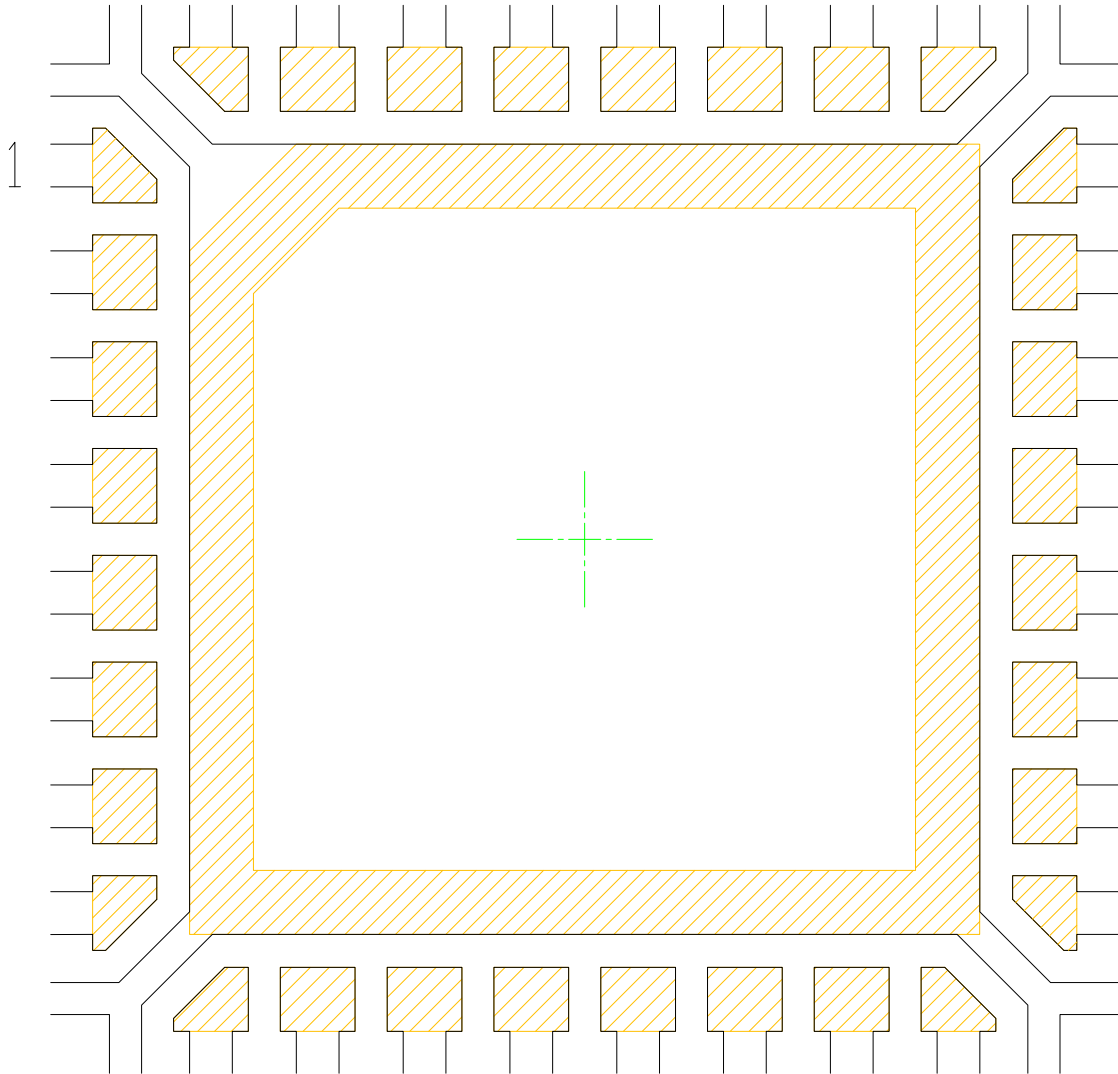



REVISIONS		
REV	DESCRIPTION	DATE
C	FULL THICKNESS SAW STREET	8-21-2017



 NiPdAu PLATING

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CUSTOMER: xxxxx	DOCUMENT #:	 www.promex-ind.com	
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 3.70 x 3.70 mm		
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 3.50 x 3.50 mm	TITLE QFN 32L 5x5 mm 0.50 PITCH BOND SHELL	
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING	LEADFRAME P/N: 235-00189	
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu	REV 00	
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH	DO NOT SCALE	
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm	FILE NAME 32L-QFN-5X5-50P-BD.DWG	SHEET 1 OF 1